

Class 1

The engineering printed board layout or check plot shall serve as the master drawing and be supplemented with manufacturing instructions and other pertinent notes to provide the necessary information to manufacture the board.





Class 2

The master drawing shall describe the physical board details, if etchback is required, the location of traceability markings, and provide separate views of each conductor layer of the printed board. Any and all pattern features not controlled by hole size and locations shall be adequately dimensioned either specifically, by notes, or by reference to a grid system used in the design of the boards. The plating and coating thickness shall be specified. Quality conformance test circuitry may also be included on the master drawing, when required. The information in Table 4-2 may be used as a guide.





Class 3

The master drawing shall describe the board in accordance with Table 4-2. Quality conforman ce test circuitry in accordance with the design standard shall be included. Test circuitry shall reflect the design of the boards and all manufacturing processes, such as drilling, plating, etching, fusing, ground/voltage planes, separate fabricated layers, permanent coatings (solder mask) etc. The master drawing shall also indicate the process allowances that were used in the design or artwork preparation of the printed board.





Class 3 (continued)

The master pattern drawing, part of the master drawing set, may be supplied using one of the following methods: reproductions of the layer image(s) reproduced using photographic techniques or pen plotted; or supplied as electronic data. Any and all pattern features not controlled by hole sizes and locations shall be adequately dimensioned either specifically, by note, or by reference to a grid system used in the design of the boards.

